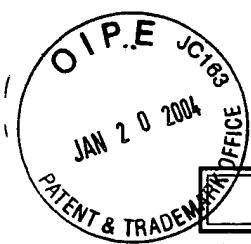


## ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention	PLANARIZED SEMICONDUCTOR INTERCONNECT TOPOGRAPHY AND METHOD FOR POLISHING A METAL LAYER TO FORM INTERCONNECT						
Application Number:	09/779123						
Confirmation Number:	9269						
First Named Applicant:	Anantha Sethuraman						
Attorney Docket Number:	5298-02502						
Art Unit:	2823						
Examiner:	Hsien-Ming Lee						
Search string:	( 5958794 or 5972124 ).pn.						
<b>US Patent Documents</b>							
Note: Applicant is not required to submit a paper copy of cited US Patent Documents							
init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	5958794	1999-09-28	Bruxvoort et al.			
	2	5972124	1999-10-26	Sethuraman et al.			
<b>Signature</b>							
Examiner Name					Date		



## FEE TRANSMITTAL

Electronic Version v08  
Stylesheet Version v08.0

Title of Invention	PLANARIZED SEMICONDUCTOR INTERCONNECT TOPOGRAPHY AND METHOD FOR POLISHING A METAL LAYER TO FORM INTERCONNECT	
Application Number:	09/779123	
Date:	2001-02-07	
First Named Applicant:	Anantha R. Sethuraman	
Attorney Docket Number:	5298-02502	
Art Unit:	2823	
Examiner:	Hsien-Ming Lee	

### TOTAL FEE AUTHORIZED \$180

Patent fees are subject to annual revisions on or about October 1st of each year.

#### BASIC FILING FEE

Fee Description	Fee Code	Amount \$	Fee Paid \$
Submission Of Information Disclosure Stmt Fee	1806	180	180

#### AUTHORIZED BILLING INFORMATION

The commissioner is hereby authorized to charge indicated fees and credit any overpayments to:

Deposit account number: 032769

Access Code \*\*\*\*\*

Deposit name: Conley Rose, P.C.

Deposit authorized name: Kevin L. Daffer

Signature: Kevin L. Daffer

Date (YYYYMMDD): 2004-01-20



1FW

# Electronic Filing System (EFS) Data

## Electronic Patent Application Submission

### USPTO Use Only

EFS ID: 53978  
Application ID: 09779123   
Title of Invention: PLANARIZED SEMICONDUCTOR  
INTERCONNECT TOPOGRAPHY  
AND METHOD FOR POLISHING A  
METAL LAYER TO FORM  
INTERCONNECT  
First Named Inventor: Anantha Sethuraman  
Domestic/Foreign Application: Domestic Application  
Filing Date: 2001-02-07  
Effective Receipt Date: 2004-01-20  
Submission Type: Information Disclosure  
Statement  
Filing Type:  
Confirmation number: 9269  
Attorney Docket Number: 5298-02502  
Total Fees Authorized: 180.0  
Payment Category: Deposit Account  
Deposit Account Number: 32769  
Deposit Account Name: Kevin L. Daffer  
Access Code: \*\*\*\*  
RAM Payment Status: RAM success  
RAM User ID: EFSPROD  
RAM Accounting Date: 2004-01-20  
RAM Sequence Number: 4

Digital Certificate Holder: cn=Kevin L. Daffer,ou=Registered Attorneys,ou=Patent and Trademark  
Office,ou=Department of Commerce,o=U.S. Government,c=US  
Certificate Message Digest: 9099fb8e14cf0e12f779738052769534f3ce595c



## TRANSMITTAL

Electronic Version v1.1  
Stylesheet Version v1.1.0

Title of Invention	PLANARIZED SEMICONDUCTOR INTERCONNECT TOPOGRAPHY AND METHOD FOR POLISHING A METAL LAYER TO FORM INTERCONNECT	
Application Number:	09/779123	
Date:	2001-02-07	
First Named Applicant:	Anantha R. Sethuraman	
Confirmation Number:	9269	
Attorney Docket Number:	5298-02502	
<p>I hereby certify that the use of this system is for OFFICIAL correspondence between patent applicants or their representatives and the USPTO. Fraudulent or other use besides the filing of official correspondence by authorized parties is strictly prohibited, and subject to a fine and/or imprisonment under applicable law.</p> <p>I, the undersigned, certify that I have viewed a display of document(s) being electronically submitted to the United States Patent and Trademark Office, using either the USPTO provided style sheet or software, and that this is the document(s) I intend for initiation or further prosecution of a patent application noted in the submission. This document(s) will become part of the official electronic record at the USPTO.</p>		
Submitted by:	Elec. Sign.	Sign. Capacity
Kevin L. Daffer Registered Number: 34146	Kevin L. Daffer	Attorney
Documents being submitted	Files	
us-fee-sheet	529802502IDS-usfees.xml us-fee-sheet.xsl us-fee-sheet.dtd	
us-ids	529802502IDS-usidst.xml us-ids.dtd us-ids.xsl	

Comments